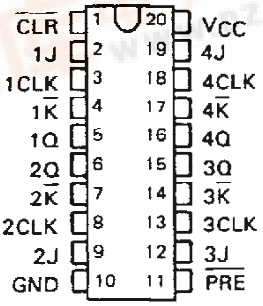
SN54276, SN74276
QUADRUPLE J-$\overline{K}$ FLIP-FLOPS

SDLS091

OCTOBER 1976 – REVISED MARCH 1988

- Four J-$\overline{K}$ Flip-Flops in a Single Package . . . Can Reduce FF Package Count by 50%
- Separate Negative-Edge-Triggered Clocks with Hysteresis . . . Typically 200 mV
- Typical Clock Input Frequency . . . 50 MHz
- Fully Buffered Outputs

SN54276 . . . J PACKAGE
SN74276 . . . N PACKAGE
(TOP VIEW)



description

These quadruple TTL J-$\overline{K}$ flip-flops incorporate a number of third-generation IC features that can simplify system design and reduce flip-flop package count by up to 50%. They feature hysteresis at each clock input, fully buffered outputs, and direct clear capability, and are presettable through a buffer that also features an input hysteresis loop. The negative-edge-triggering clocks are directly compatible with earlier Series 54/74 single and dual pulse-triggered flip-flops. These circuits can be used to emulate D- or T-type flip-flops by hard-wiring the inputs, or to implement asychronous sequential functions.

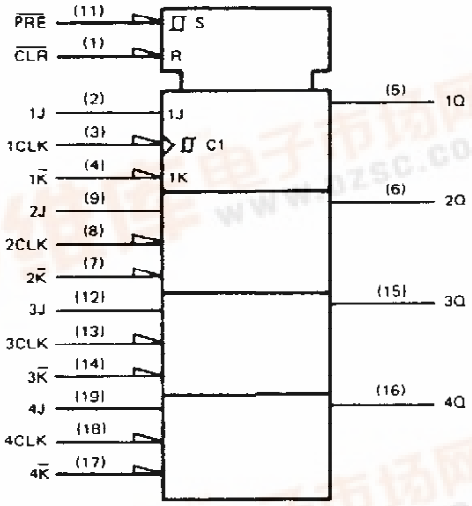
The SN54276 is characterized for operation over the full military temperature range of −55°C to 125°C; the SN74726 is characterized for operation from 0°C to 70°C.

FUNCTION TABLE (EACH FLIP-FLOP)

COMMON INPUTS		INPUTS			OUTPUT
$\overline{PRE}$	$\overline{CLR}$	CLK	J	$\overline{K}$	Q
L	H	X	X	X	H
H	L	X	X	X	L
L	L	X	X	X	H†
H	H	↓	L	H	Q_0
H	H	↓	H	H	H
H	H	↓	L	L	L
H	H	↓	H	L	TOGGLE
H	H	H	X	X	Q_0

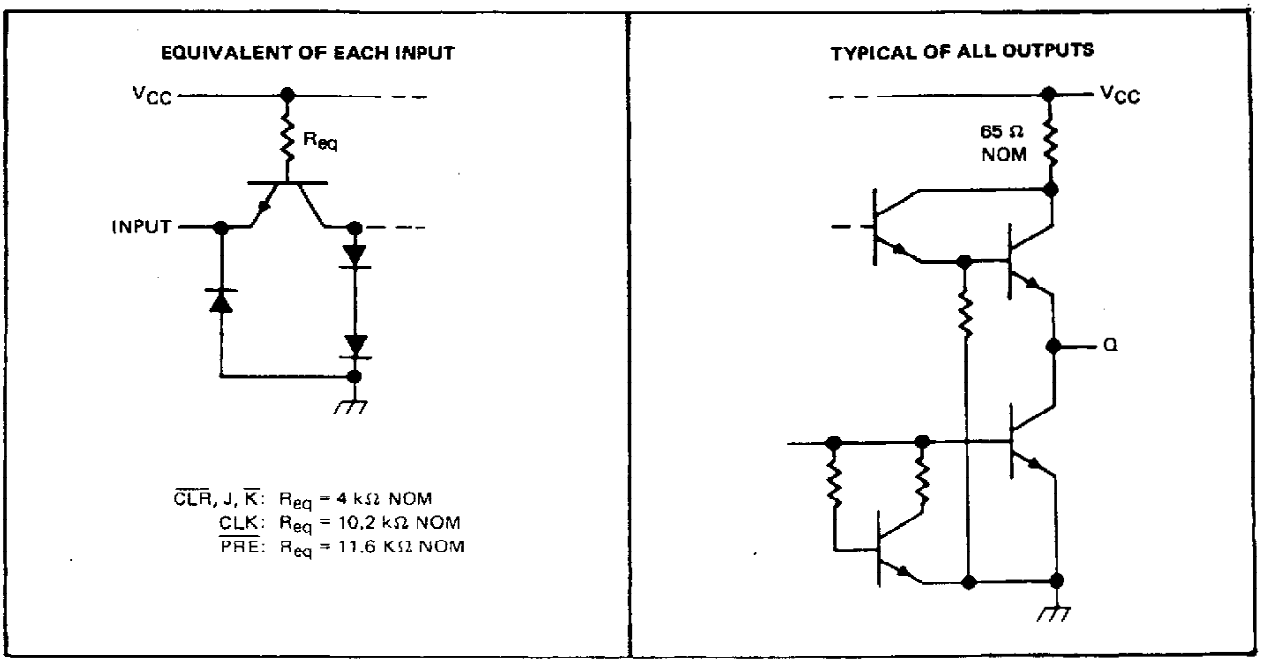
† This configuration is nonstable; that is, it may not persist when preset and clear return to their inactive (high) level.

logic symbol‡



‡This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage . . . . . 5.5 V
Operating free-air temperature range: SN54276 . . . . . −55°C to 125°C
SN74276 . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SN54276			SN74276			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}		4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}				−800			−800	μA
Low-level output current, I_{OL}				16			16	mA
Clock frequency		0		35	0		35	MHz
Pulse width, t_w	Clock high	13.5			13.5			ns
	Clock low	15			15			
	Preset or clear low	12			12			
Setup time, t_{su}	J, K inputs	3↓			3↓			ns
	Clear and preset inactive state	10↓			10↓			
Input hold time, t_h		10↓			10↓			ns
Operating free-air temperature, T_A		−55		125	0		70	°C

↓ The arrow indicates that the falling edge of the clock pulse is used for reference.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		MIN	TYP‡	MAX	UNIT
V_{IH}	High-level input voltage			2			V
V_{IL}	Low-level input voltage					0.8	V
V_{IK}	Input clamp voltage	V_{CC} = MIN,	I_I = −12 mA			−1.5	V
V_{OH}	High-level output voltage	V_{CC} = MIN, V_{IL} = 0.8 V,	V_{IH} = 2 V, I_{OH} = −800 μA	2.4	3.4		V
V_{OL}	Low-level output voltage	V_{CC} = MIN, V_{IL} = 0.8 V,	V_{IH} = 2 V, I_{OL} = 16 mA		0.2	0.4	V
I_I	Input current at maximum input voltage	V_{CC} = MAX,	V_I = 5.5 V			1	mA
I_{IH}	High-level input current	V_{CC} = MAX,	V_I = 2.4 V			40	μA
I_{IL}	Low-level input current	V_{CC} = MAX,	V_I = 0.4 V			−1.6	mA
I_{OS}	Short-circuit output current§	V_{CC} = MAX		−30		−85	mA
I_{CC}	Supply current	V_{CC} = MAX			60	81	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.
§ Not more than one output should be shorted at a time.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{max}	Maximum clock frequency	C_L = 15 pF, R_L = 400 Ω, See Note 2	35	50		MHz
t_{PLH}	Propagation delay time, low-to-high-level output from preset			15	25	ns
t_{PHL}	Propagation delay time, high-to-low-level output from clear			18	30	ns
t_{PLH}	Propagation delay time, low-to-high level output from clock			17	30	ns
t_{PHL}	Propagation delay time, high-to-low level output from clock			20	30	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

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